

Radio Frequency Filter

5 Background of the Invention

The present invention is generally related to radio frequency (RF) filters. Divisional application no. 8924695 relates to a radio frequency combiner.

10 In order to combine a number of RF transmitters, the RF signals from each transmitter must be isolated from one another to prevent intermodulation and possible damage to the transmitters. RF filters of the air-filled cavity type may be utilized to provide isolation between the RF  
15 transmitters. Each such cavity filter is tuned to pass only the RF signal from the transmitter to which it is connected, each RF transmitter producing a different frequency RF signal. The outputs from each filter may be combined and coupled to a common antenna by combining  
20 apparatus of the type shown and described in US patent no. 4,375,622. Each filter is coupled to this combiner by precisely equal lengths of coaxial cable. The combiner is tuned by means of manually adjustable transmission lines or stubs, which likewise are coupled to the combiner by a  
25 coaxial cable.

A conventional mechanism utilized to temperature compensate such cavity filters is described in US Patent No. 4,024,481. However, such air-filled cavity filters are both expensive and relatively large in size such that these  
30 cavity filters consume an inordinate amount of precious space at remote antenna sites located on top of buildings and mountains.

The size of such RF filters can be reduced by utilising a ceramic resonator. One such filter utilising a ceramic resonator is described in US Patent No. 4,241,322. Although providing a more compact filter, the ceramic resonator in such a filter can experience large shifts in resonant frequency since it is not compensated for ambient and RF power dissipation induced temperature changes. Another filter described in US Patent No. 4,019,161 utilises conventional mechanisms to temperature compensate a ceramic resonator mounted on a micro-integrated circuit substrate, but does not provide for dissipation of heat in the ceramic resonator.

### Summary of the Invention

Accordingly, it is an object of the present invention to provide an improved ceramic resonator.

According to the present invention there is provided an RF filter according to claim 1.

A resonator, a first shield plate and a first compensating disc may be provided having concentrically aligned holes therein into which a tuning core is inserted for adjusting the resonant frequency of the ceramic resonator. The resonator, first and second compensating discs, first and second shield plates and tuning core are enclosed by a metallic housing which preferably maintains the spatial relationship therebetween. Input and output signals may be coupled to the RF filter by means of respective input and output coupling loops which may be located at any suitable location on the metallic housing.

Brief Description of the Drawings

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Figure 1 is an exploded perspective view of the preferred embodiment of the RF filter of the present invention.

Figure 2 is is a block diagram of combining  
10 apparatus advantageously utilizing RF filters illustrated in Figure 1 for coupling RF signals from respective RF transmitters to a combiner for application to a common antenna.

Figure 3 is a top view of a microstrip combiner and  
15 the RF filter illustrated in Figure 1.

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Figure 4 is a top view of a coupling loop circuit board used in the microstrip combiner illustrated in Figure 3.

Figure 5 is a bottom view of the circuit board 5 illustrated in Figure 4.

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Figure 6 is a top view of the microstrip circuit board used in the microstrip combiner illustrated in Figure 3.

5        Figure 7 illustrates the tuning circuitry used to tune the microstrip combiner illustrated in Figure 3.

Figure 8 is an exploded view of the tuning circuitry and apparatus used to tune the microstrip combiner illustrated in Figure 3.

10       Figure 9 is a bottom view of the microstrip combiner illustrated in Figure 3.

#### Description of the Preferred Embodiment

15       In Figure 1, there is illustrated an exploded view of an RF filter 100 that is particularly well adapted for use in the antenna combining apparatus in Figure 2 for combining two or more RF transmitters operating in the frequency range from 870-896 mHz. The nominal unloaded Q of filter 100 over the ambient temperature  
20       range of  $-30^{\circ}$  to  $+60^{\circ}\text{C}$  is a maximum of 55 kHz with respect to the nominal frequency at room temperature. The nominal dimensions of filter 100 are 5.5" (135 mm) in diameter and 3" (73.5 mm) in length, as compared to 6" (147 mm) in diameter and 13" (319 mm) in length for a conventional air-filled cavity filter. In addition to  
25       being much smaller than an equivalent air-filled cavity filter, filter 100 results in a materials cost saving of 60% over the equivalent air-filled cavity filter.

Referring to Figure 1, filter 100 includes a ceramic resonator 116 which is sandwiched between a first compensating disc 114 and  
30       second compensating disc 120. Resonator 116 is preferably comprised of a ceramic compound having a dielectric constant of at least thirty-six. Commercially available ceramic compounds such as those including pre-selected amounts of barium

oxide, titanium oxide, zirconium oxide, zinc oxide, lanthanum oxide and/or tin oxide may be used. For example, suitable ceramic compounds are described in U.S. patent no. 3,938,064 and in an article by G. H. Jonker and W. Kwestroo, entitled "The Ternary Systems BaO-TiO<sub>2</sub>-SnO<sub>2</sub> and BaO-TiO<sub>2</sub>-ZrO<sub>2</sub>", published in the Journal of American Ceramic Society, Volume 41, Number 10, October 1958, at pages 390-394 (incorporated herein by reference thereto). Of the ceramic compounds described in the Jonker article, the compound Ba<sub>2</sub>Ti<sub>9</sub>O<sub>20</sub> in Table VI having the composition 18.5 mole percent BaO, 77.0 mole percent TiO<sub>2</sub> and 4.5 mole percent ZrO<sub>2</sub> and having a dielectric constant of forty may be used for resonator 116. Many of the other ceramic compounds in the Jonker article may likewise be utilized. Compensating discs 114 and 120 are preferably comprised of alumina (Al<sub>2</sub>O<sub>3</sub>) since alumina exhibits low dielectric loss, high thermal conductivity relative to ceramic resonator 116 and a positive dielectric temperature coefficient with respect to that of ceramic resonator 116.

According to an important feature of filter 100, the negative dielectric temperature coefficient of ceramic resonator 116 can be substantially compensated by the positive dielectric temperature coefficient of alumina compensating discs 114 and 120. That is, the -36 ppm/°C dielectric temperature coefficient of the ceramic resonator 116 can be substantially offset by the +113 ppm/°C dielectric temperature coefficient of the alumina compensating discs 114 and 120. As is known in the art, the dielectric temperature coefficient of a dielectric material is proportional to the physical size. Therefore, the desired compensation is achieved by selecting the thickness of the alumina compensating discs 114 and 120 so that their dielectric temperature coefficient is substantially the same in magnitude but

opposite in sign to the dielectric temperature coefficient of resonator 116.

Moreover, the alumina compensating discs 114 and 120 not only provide for ambient temperature compensation, but also minimize temperature rise due to RF power dissipation of ceramic resonator 116 by providing a low thermal resistance between ceramic resonator 116 and the top and bottom covers 112 and 128 of the filter housing, and minimize the overall RF loss of the filter by supporting the resonator 116 away from the loss-inducing aluminum covers 112 and 128. Since alumina conducts heat much better than air, alumina discs 114 and 120 efficiently conduct heat from resonator 116 to covers 112 and 128 and housing 124, thereby minimizing the temperature rise in resonator 116. A compressive force exerted by springs 144-147 of shield plate 142 maintains good thermal contact between the resonator 116 and covers 112 and 128, such that the thermal resistance between resonator 116 and covers 112 and 128 is less than  $1^{\circ}\text{C}/\text{W}$  (i.e.  $0.68^{\circ}\text{C}/\text{W}$  predicted by design analysis). Therefore, according to another feature of filter 100, high power transmitters can be coupled to filter 100 since the temperature rise due to power dissipation in the ceramic resonator 116 is minimized by the relatively low thermal resistance between ceramic resonator 116 and the top and bottom covers 112 and 128. For example, with twelve watts of RF energy dissipated in the filter 100, the temperature of ceramic resonator 116 will rise only  $8^{\circ}\text{C}$  above ambient temperature and the frequency of filter 100 will drift approximately 8kHz due to RF energy dissipation.

Referring back to Figure 1, the housing for filter 100 includes top cover 112, housing 124 and bottom cover 128 which are preferably cast from aluminum alloy (eg., #380 aluminum alloy). Top cover 112 includes a top hat 132 into which a threaded bushing 133 preferably

comprised of brass is press fit. Top cover 112 also includes a recessed portion for receiving shield plate 142. Shield plate 142 includes three tabs 160, 161 and 162 for positioning disc 114. Likewise, bottom cover 128  
5 includes a recessed area for receiving shield plate 148 and a portion of disc 120. The raised step 121 of disc 120 inserts into the hole in resonator 116. Tabs 160, 161 and 162 of shield plate 142, raised step 121 of disc 120 and recessed area of bottom cover 128 maintain  
10 resonator 116 in proper spatial relationship with discs 114 and 120. Top cover 112 is attached to housing 124 by means of four screws which insert into four holes, e.g. 107 and 108 at the periphery of cover 112 and housing 124. An O-ring 150 provides a moisture seal and, if  
15 impregnated or coated with conductive material, an electromagnetic seal between top cover 112 and housing 124. Bottom cover 128 is preferably cast with housing 124, but in other embodiments of filter 100, bottom cover 128 may be separate from housing 124 and attached thereto  
20 by means of screws.

In order to produce a high-Q filter, the housing of RF filters are typically made from or plated on their internal surfaces with a highly conductive material such as copper. For detailed filter design information, refer  
25 to the following two articles: "Design of Cylindrical Dielectric Resonators in Inhomogeneous Media," by Rene R. Bonetti and Ali E. Atia, IEEE Transactions on Microwave Theory and Techniques, Volume MTT-29, No. 4, pp. 323-326, April 1981; and "Microwave Bandpass Filters Containing  
30 High-Q Dielectric Resonators," by Seymour B. Cohn, IEEE Transactions on Microwave Theory and Techniques, Volume MTT-16, No. 4, pp. 218-227, April 1968. Although aluminum is not as good a conductor as copper, aluminum is castable and less expensive than copper. In the  
35 preferred embodiment of filter 100, housing parts 112, 124 and 128 are comprised of #380 aluminum alloy.

However, due to lower conductivity of aluminum, the housing parts 112, 124 and 128 dissipate some of the external field of the resonator 116, thereby lowering the Q of filter 100 by as much as nine percent (9%).

5       According to another feature of filter 100, lowering of the Q of filter 100 due to the aluminum housing parts 112, 124 and 128 is substantially avoided by utilizing a highly conductive shield plate 142 between disc 114 and top cover 112 and another highly conductive shield plate  
10   148 between disc 120 and bottom cover 128. A third highly conductive shield plate 140 is also disposed on the top surface of tuning core 118. Shield plates 140, 142 and 148 are preferably comprised of copper (silver or gold are also suitable) to provide the desired low-loss  
15   path for the external field at the top surface of tuning core 118, the top surface of disc 114, and the bottom surface of disc 120, respectively. In other embodiments, shield plates 140, 142 and 148 could be constructed of a non-conductor and plated with copper, silver or gold, all  
20   of which have a conductivity greater than  $1.3 \times 10^7$  mho/m, the conductivity of #380 aluminum alloy. By utilizing copper shield plates 140, 142 and 148, housing parts 112, 124 and 128 may be made from aluminum or other low conductivity metallic materials which are much  
25   cheaper than copper or copper plated materials without degrading the Q of filter 100. Therefore, filter 100 is relatively inexpensive while at the same time having a relatively high-Q.

      Copper shield plate 142 also includes three tabs 160,  
30   161 and 162 for positioning disc 114, and further includes raised portions 144, 145, 146 and 147 for producing a spring force when cover 112 and housing 124 are assembled. Thus, housing parts 112, 124 and 128 totally enclose the sandwiched ceramic resonator 116 and  
35   compress raised portions 144, 145, 146 and 147 of plate 142 to produce a spring force for maintaining the spatial

relationship between ceramic resonator 116 and alumina compensating discs 114 and 120. Moreover, raised portions 144, 145, 146 and 147 of copper shield plate 142 are made large enough to conduct heat from disc 114 to  
5 top cover 112 for minimizing temperature rise of resonator 116 due to power dissipation. In other embodiments, ceramic resonator 116 and alumina compensating discs 114 and 120 may be maintained in spatial relationship with one another by bonding them  
10 together with a suitable adhesive such as glass frit or bonding film.

The resonant frequency of ceramic resonator 116 may be adjusted by means of threaded tuning shaft 102 and dielectric tuning core 118 attached thereto. The  
15 resonant frequency of resonator 116 decreases as tuning core 118 is inserted into substantially concentric holes in shield plate 142, disc 114 and resonator 116. In the preferred embodiment, disc 120 does not include a hole for tuning core 118 since tuning core 118 need not be  
20 inserted into disc 120 in order to achieve the desired tuning range. In other embodiments, disc 120 may also have a hole concentric with the holes in disc 114 and resonator 116. Tuning core 118 is preferably comprised of a low-loss ceramic material, such as, for example, the  
25 same ceramic material used for resonator 116. Tuning core 118 not only changes the resonant frequency, but also eliminates some spurious resonant modes (by keeping the overall housing dimensions constant as the frequency of resonator 116 is tuned), minimizes resonator de-Q-ing  
30 (because it employs a low-loss ceramic material), and allows discs 114 and 120 to be in good thermal contact with resonator 116 over its entire top and bottom surfaces. Although resonator 116 is preferably tuned by means of tuning core 118, other suitable conventional  
35 tuning apparatus may also be utilized.

Tuning shaft 102 is threaded and mates with a correspondingly threaded brass bushing 133, which is press fit into top hat 132 of top cover 112. The position of the shaft 102 may be fixedly held by  
5 tightening nut 104 and washer 106. Tuning shaft 102, housing 124 and covers 112 and 128 are preferably comprised of aluminum. Since aluminum is non-ferrous, tuning shaft 102, housing 124 and covers 112 and 128 experience less Q degradation when subjected to external  
10 magnetic fields if comprised of aluminum rather than steel or other ferrous materials.

Tuning shaft 102, tuning core 118, bushing 133, compensating discs 114 and 116 and housing parts 112, 124 and 128 may also be comprised of pre-selected materials  
15 each having different coefficients of expansion for compensating for changes in the resonant frequency of resonator 116 with ambient temperature. For example, the movement of tuning core 118 over ambient temperatures may be partially compensated by bushing 133 and the height of  
20 top hat 132 of top cover 112. That is, the desired temperature compensation is achieved by the difference in the coefficient of expansion between, and the respective sizes of, bushing 133, tuning shaft 102, top hat 132 and tuning core 118. This arrangement can compensate for a  
25 worst case change of 1.1 ppm/°C of the frequency temperature coefficient of filter 100.

The dimensions of the various elements of an embodiment filter 100 for operation at frequencies between 865-902 MHz are listed below in Table I. In this  
30 embodiment, the resonator 116 and tuning core 118 are comprised of the ceramic compound, discs 114 and 120 of alumina, bushing 133 of brass, tuning shaft 102 of aluminum and the housing parts 112, 124 and 128 of #380 aluminum alloy. The exact dimensions of the elements of  
35 an embodiment of filter 100 will vary depending on the desired frequency of operation and the materials chosen for each of the elements.

Table 1 Filter Dimensions in Inches  
(millimetre values in brackets)

| <u>Element</u> |                  | <u>Outer Diameter</u> | <u>Inner Diameter</u> | <u>Length</u> |
|----------------|------------------|-----------------------|-----------------------|---------------|
| 5              | Resonator 116    | 2.68 (66)             | 1.26 (31)             | 0.77 (19)     |
|                | Disc 114         | 2.80 (69)             | 1.26 (31)             | 1.14 (28)     |
|                | Disc 120         | 2.80 (69)             | -                     | 1.13 (27.7)   |
|                | Core 113         | 1.20 (29)             | -                     | 1.37 (34)     |
|                | Shaft 102        | 0.38 (9.3)            | -                     | 2.30 (56)     |
|                | Housing 124      | 5.62 (138)            | 5.50 (135)            | 3.00 (74)     |
|                | Top Cover 112    | 5.62 (138)            | 1.50 (37)             | 0.90 (22)     |
|                | Bottom Cover 128 | 5.62 (138)            | -                     | -             |

Referring next to Figure 2, there is illustrated antenna combining apparatus for coupling RF transmitters 201-205 having different signal frequencies to a common antenna 231. Filters 211-215 are preferably filters 100 embodying the present invention. Combiner 221 is preferably the microstrip combiner 300 shown in Figure 3. Combiner 221 may also be a suitable conventional antenna combiner such as that shown and described in the U.S. Patent No. 4,375,622, which is incorporated herein by reference thereto. By utilizing the RF filter 100 for filters 211-215, the overall size and space requirements of the combining apparatus in Figure 2 can be significantly reduced. Since space is at a premium in remotely located antenna sites, a substantial cost savings can be realized by utilizing the filter 100.

Referring next to Figure 3, there is illustrated a top view of filter 100 and microstrip combiner 300 embodying the present invention. The top cover 112 of filter 100 is removed to more clearly show coupling loops 122 and 311. Two screws insert into holes 139 for mounting each of the five filters 100 to a suitable mounting panel. Four screws insert into holes 108 for mounting top cover 112 to housing 124.

RF signals are coupled to filter 100 in Figure 3 by means of coupling loop 122 of connector 136 and coupling loop 311 on circuit board 301. In the preferred

embodiment of filter 100, coupling loops 122 and 311 are located substantially in the same plane as the center of resonator 116 and are disposed at approximately  $120^\circ$  with respect to one another as shown in Figure 3. Since  
5 the exact location of coupling loop 122 is not critical to operation of filter 100, coupling loop 122 may also be located on housing 124 at any suitable location in the plane of the center of resonator 116, as long as coupling loop 122 and coupling loop 311 are sufficiently separated  
10 to avoid undesirable direct coupling.

Combiner 300 in Figure 3 includes substrate circuit board 310 (see also Figure 6), metal housing 320 and five coupling circuit boards 301-305 (see also Figures 4 and 5). An output connector 902 (see Figure 9) is soldered  
15 to the center of substrate circuit board 310 and extends out of the underside of metal housing 320. Board 301 is preferably comprised of a dielectric material suitable for microstrip transmission lines. In the preferred embodiment of combiner 300, substrate circuit board 310  
20 is comprised of alumina. Coupling circuit boards 301-305 are attached to housing 320 with a screw. Strap 314 is soldered between coupling loop 312 and the ground on board 310, and strap 313 is soldered between coupling loop 312 and a corresponding microstrip line on board  
25 310. Similar straps are used to couple boards 301, 303, 304 and 305 to board 310. Housing 320 is attached by two screws to platform 154 on each filter 100. Once attached to each of five filters 100, housing 320 is enclosed by attaching a metal top plate 330 with screws (see Figure  
30 8).

Each coupling circuit board 301-305 inserts into corresponding apertures 152 in the housing 124 of filter 100, and are each moisture sealed by a rubber boot, e.g. 340. A transmitter signal from a transmitter, e.g. 201  
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is applied to connector 136 and coupled to resonator 116 by coupling loop 122. The filtered transmitter signal is detected by  
5 coupling loop 311 on circuit board 301. Microstrip circuitry on board 310 combines the five transmitter signals and couples them to output connector 902 (see Figure 9).

Referring next to Figures 4 and 5, there is illustrated in more detail coupling circuit board 301 and coupling loop 301. Coupling  
10 loop 311 is metallic plating, preferably copper plating, on the top surface of board 301, preferably random-fiber PTFE with a nominal dielectric constant of 2.1. Board 301 is attached to housing 320 of combiner 300 by a screw which inserts into hole 402. Board 301 contains a fifty-ohm microstrip transmission line 411, coupling loop  
15 311 and ground pad 413. As shown in Figure 5, only portion 502 of the bottom surface of board 301 is copper plated. Portion 502 is opposite to fifty-ohm microstrip transmission line 411 and ground pad 413. That is, there is no plating on the bottom surface of board 301 opposite to coupling loop 311.

Referring next to Figure 6, there is illustrated in more detail  
20 substrate circuit board 310. Board 310 is copper-plated on its bottom side and includes five fifty-ohm microstrip transmission lines 601-605 of equal length on its top side for coupling corresponding filtered transmitter signals to junction 620. Junction  
25 620 has a hole in its center for accepting the center conductor of the output connector 902 (see Figure 9). Board 310 also includes serpentine transmission line 610 for tuning junction 620.

Referring next to Figure 7, there is illustrated unique variable  
30 reactance tuning circuitry including serpentine transmission line 610 and dielectric tuning plate 630 for tuning microstrip combiner 300 in Figure 3. Line 610 is a short-circuited

transmission line of length  $3\lambda/4$ , having infinite input reactance when half of its physical length  $L$  is covered by dielectric tuning plate 630. Line 610 may be configured in a serpentine pattern as illustrated or may simply be straight or any other suitable shape dictated by a proposed application thereof. Together line 610 and tuning plate 630 provide an impedance whose reactance may be varied from inductive to capacitive simply by moving plate 630 relative to line 610, e.g. from position B to position C.

The unique variable reactance tuning circuitry in Figure 7 presents an input impedance of  $Z_I = jX$ , where the value of the input reactance  $X$  is varied by moving plate 630 relative to line 610. According to the preferred embodiment of the present invention, the amount of variation of the input reactance  $X$  is determined by the length of line 610 and the dielectric constant of tuning plate 630. Increasing either the length of line 610 or the dielectric constant of plate 630 increases the reactance tuning range and vice versa. The center of the reactance tuning range is determined by the impedance terminating line 610 and the length of line 610. In general, the input impedance  $Z_I$  may be calculated by the equation:

$$(1) \quad Z_I = Z_0 \left[ \frac{Z_T/Z_0 + j \tan \beta L}{1 + (Z_T/Z_0) j \tan \beta L} \right], \text{ where:}$$

$$\beta L = 2\pi(f/c) (L_1/\epsilon_{r1} + L_2/\epsilon_{r2});$$

$f$  is frequency;

$c$  is the speed of light;

$Z_0$  is the characteristic impedance of line 630;

$Z_T$  is the impedance terminating line 630;

Line 630 has a physical length of  $L = L_1 + L_2$ ; and  $\epsilon_{r1}$  and  $\epsilon_{r2}$  are the effective dielectric constants of the covered and uncovered portions  $L_1$  and  $L_2$ , respectively.

In the preferred embodiment of the unique variable reactance tuning circuitry in Figure 7, tuning transmission line 610 is terminated by a short circuit, i.e.  $Z_T = 0$ . When terminated by a short circuit, the above equation for the input impedance  $Z_I$  of line 610 reduces to:

(2)  $Z_I = jZ_0 \tan(\beta L)$ .

According to the preferred embodiment of the present invention, the center of the reactance tuning range (i.e. when plate 630 covers one-half of line 610 or  $L_1 = L_2 = L/2$ ) can be chosen as desired for each specific application of the unique variable reactance tuning circuitry in Figure 7. For the preferred embodiment of combiner 300, the center of the reactance range was chosen to be infinite reactance so that the input reactance  $X$  of the input impedance  $Z_I$  may be shifted between capacitive and inductive reactances. Since infinite reactance has no effect on operation of combiner 300, combiner 300 is tuned by shifting the input reactance  $X$  from infinite to increasing amounts of capacitive or inductive reactance to achieve the desired combiner characteristics. For any specific terminating impedance  $Z_T$ , the input impedance  $Z_I$  of the unique variable reactance tuning circuitry in Figure 7 is shifted over a range given by equation (1) above and centered about the predetermined input impedance produced when plate 630 covers one-half of tuning transmission line 610 (i.e.  $L_1 = L_2 = L/2$ ).

When used in conjunction with combiner 300, the unique tuning circuitry 610 and 630 in Figure 7 provides variable compensation for the reactance associated with the microstrip discontinuity at the junction 620 of five microstrip transmission lines 601-605. As a result, combiner 300 exhibits greater transmission efficiency

over a wider bandwidth than would be obtainable without the unique tuning circuitry described. Moreover, the filter of the  
5 present invention can be advantageously utilised in any suitable application where variable inductive and/or capacitive tuning is desired.

Referring to Figure 8, there is illustrated an exploded view of the stripline tuning circuitry and apparatus use to tune the  
10 microstrip combiner 300 illustrated in Figure 3. Top plate 330 is secured to housing 320 by means of screws. Plate 330 also includes a hole 350 for access to serpentine transmission line 610. Dielectric tuning plate 630 is bonded to block 806 by a suitable adhesive. Block 806 includes three holes, one for accepting spring 804 and the  
15 other two for posts 808 and 809. Cover plate 802 includes posts 808 and 809 and slotted holes 810 and 811. Screws insert into holes 810 and 811 for attaching cover plate 802 to top plate 330 of combiner 300. Posts 808 and 809 of plate 802 position block 806 and dielectric tuning plate 630 over serpentine transmission line  
20 610. Spring 804 forces dielectric tuning plate 630 against serpentine transmission line 610. When tuning combiner 300, the screws retaining plate 802 are loosened and plate 802 is slid back and forth in the direction of slotted holes 810 and 811 to tune combiner 300. When the desired tuning is achieved, the screws  
25 retaining plate 802 are tightened. The foregoing unique tuning apparatus and process allow combiner 300 to be quickly and accurately tuned.

Referring to Figure 9, there is illustrated a bottom view of the microstrip combiner 300 illustrated in Figure 3. Output connector  
30 902 extends from the bottom of housing 320 and provides the combined output signal of combiner 300. Connector 902 is secured to housing 320 and provides the combined output signal of combiner 300. Connector 902 is secured to housing 320 by means of nut 904.



Claims

1. A radio frequency (RF) filter comprising:  
resonating means having top and bottom surfaces  
and being comprised of a ceramic material having a  
predetermined thermal conductivity;

first and second compensating means each having  
top and bottom surfaces and being disposed above and  
below the resonating means, respectively, the bottom  
surface of the first compensating means and the top  
surface of the second compensating means being thermally  
coupled to the top and bottom surfaces of the resonating  
means, respectively, and the first and second  
compensating means being comprised of a dielectric  
material having a thermal conductivity greater than the  
thermal conductivity of air;

first and second shield means being comprised of  
a metallic material and being thermally coupled to and  
disposed above and below the first and second  
compensating means, respectively, for producing a  
low-loss electromagnetic path above and below said  
resonating means;

housing means being comprised of a metallic  
material having an electrical conductivity less than that  
of the metallic material of said first and second shield  
means and further including top, bottom and side  
surfaces;

input coupling means and output coupling means  
disposed on the side surface of said housing means  
opposite to said resonating means and at a pre-selected  
distance from one another for coupling respective input  
and output signals to said RF filter; and



said housing means substantially enclosing and retaining the resonating means between the first and second compensating means and the first and second shield means, the top and bottom surfaces of the housing means  
5 being thermally coupled to the first and second shield means, respectively, whereby a low thermal resistance path is produced between the resonating means, first and second compensating means, first and second shield means and the housing means for conducting away from said  
10 resonating means heat dissipated therein thereby minimizing the temperature rise of said resonating means due to power dissipation.

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2. The RF filter according to claim 1, wherein said resonating means, first shield means and first compensating means further include respective holes substantially concentrically aligned with one another,  
5 said RF filter further including tuning means comprised of a dielectric material and being inserted into the holes of the first compensating means, first shield means and resonating means for changing the resonating means resonant frequency.
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3. The RF filter according to claim 2, wherein said tuning means includes a tuning shaft and a tuning core, the tuning core being comprised of a ceramic material.
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4. The RF filter according to claim 3, further including third shield means comprised of a metallic material and being disposed above said tuning core for shielding said resonating means and tuning core.
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5. The RF filter according to claim 3, wherein said tuning shaft is threaded and said housing means further includes threaded bushing means adapted to receive the tuning shaft.
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6. The RF filter according to claim 5, wherein said tuning shaft, bushing means, first and second compensating means and housing means are comprised of pre-selected materials having different coefficients of expansion with temperature for compensating for changes  
30 in the resonating means resonant frequency with temperature.



7. The RF filter according to claim 1, wherein said first and second compensating means are substantially comprised of alumina.

5 8. The RF filter according to claim 1, wherein one of said first and second shield means includes spring means for producing a compressive force when retained by said housing means.

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9. A radio frequency (RF) filter comprising:

5 resonating means having top and bottom surfaces and being comprised of a ceramic material having a predetermined thermal conductivity and a predetermined rate of change of resonant frequency with temperature;

10 first and second compensating means being disposed above and below the resonating means, respectively, and each having top and bottom surfaces, the bottom surface of the first compensating means and the top surface of the second compensating means being thermally coupled to the top and bottom surfaces of the resonating means, respectively, and the first and second compensating means being comprised of a dielectric material having a rate of change of  
15 resonant frequency with temperature opposite in polarity to said predetermined rate of change, and the dielectric material of the first and second compensating means further having a thermal conductivity greater than the thermal conductivity of air;

20 first and second shield means being comprised of a metallic material and being thermally coupled to and disposed above and below the first and second compensating means, respectively, for producing a low-loss electromagnetic path above and below said resonating means; and

25 housing means being comprised of a metallic material having an electrical conductivity less than that of the metallic material of said first and second shield means and further including top, bottom and side surfaces;



input coupling means and output coupling means disposed on the side surface of said housing means opposite to said resonating means and at a pre-selected distance from one another for coupling  
5 respective input and output signals to said RF filter; and

said housing means substantially enclosing and retaining the resonating means between the first and second compensating means and the first and second shield means, the top and bottom surfaces  
10 of the housing means being thermally couple to the first and second shield means, respectively, whereby a low thermal resistance path is produced between the resonating means, first and second compensating means, first and second shield means and the housing means for conducting away from said resonating means heat  
15 dissipated therein thereby minimising the temperature rise of said resonating means due to power dissipation.

10. A radio frequency (RF) filter substantially as hereinbefore described by way of example with reference to Figure 1 of the  
20 drawings.

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